

2.8X0.8mm RIGHT ANGLE SMD CHIP LED **LAMP**



ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Part Number: KA-2810AZGS-G

Green

Features

- 2.8mmX0.8mm right angle SMT LED, 1.2mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

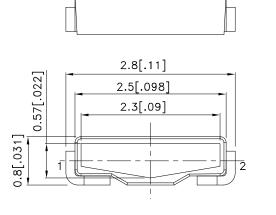
The Green source color devices are made with InGaN Light Emitting Diode.

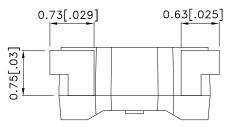
Static electricity and surge damage the LEDS.

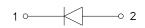
It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

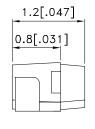
All devices, equipment and machinery must be electrically grounded.

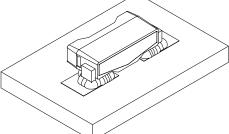
Package Dimensions











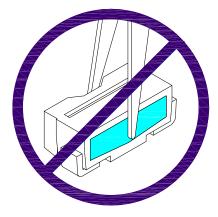
- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.1 (0.0039")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

SPEC NO: DSAK5173 **REV NO: V.5B DATE: MAR/21/2013** PAGE: 1 OF 6 **APPROVED: WYNEC CHECKED: Allen Liu** DRAWN: Y.Liu ERP: 1201005947

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.



2. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

Detailed application notes are listed on our website. http://www.kingbright.com/application notes

 SPEC NO: DSAK5173
 REV NO: V.5B
 DATE: MAR/21/2013
 PAGE: 2 OF 6

 APPROVED: WYNEC
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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
KA-2810AZGS-G	Green (InGaN)	Water Clear	700	1200	110°

- 1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
 2. Luminous intensity/ luminous Flux: +/-15%.
 3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	520		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	525		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	35		nm	IF=20mA
С	Capacitance	Green	100		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	3.2	4	V	IF=20mA
lR	Reverse Current	Green		50	uA	V _R =5V

Notes:

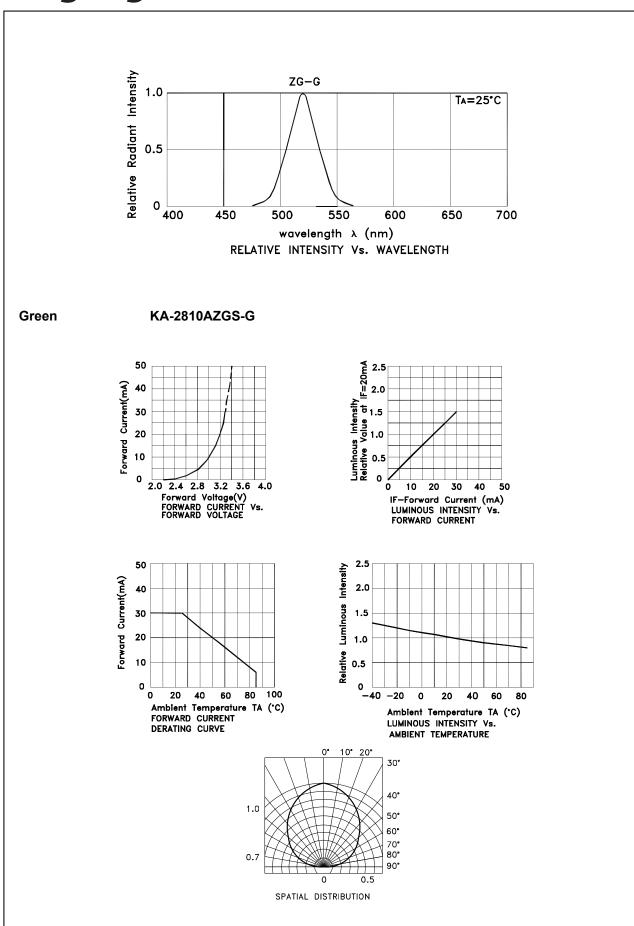
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	120	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	100	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

REV NO: V.5B DATE: MAR/21/2013 PAGE: 3 OF 6 SPEC NO: DSAK5173 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: Y.Liu ERP: 1201005947

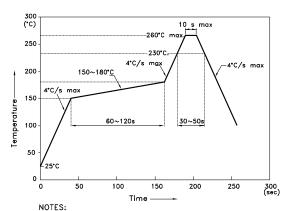


SPEC NO: DSAK5173 APPROVED: WYNEC REV NO: V.5B CHECKED: Allen Liu DATE: MAR/21/2013 DRAWN: Y.Liu PAGE: 4 OF 6 ERP: 1201005947

KA-2810AZGS-G

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



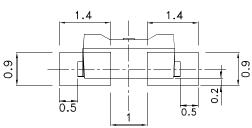
- NOTES:

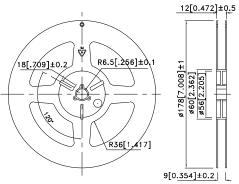
 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

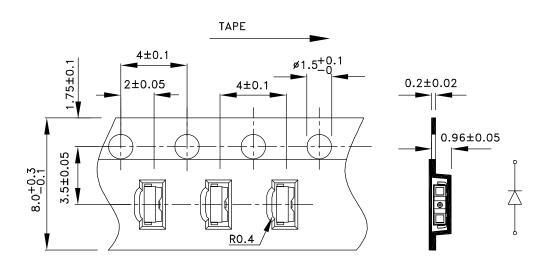
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)





Reel Dimension

Tape Dimensions (Units : mm)

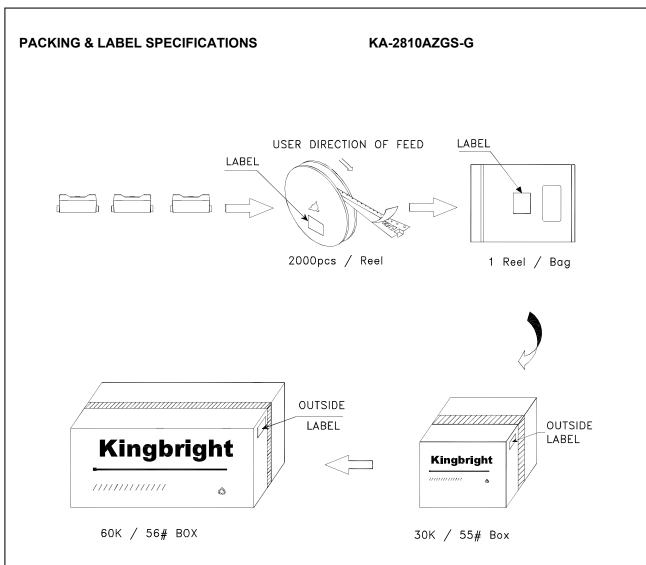


SPEC NO: DSAK5173 APPROVED: WYNEC

REV NO: V.5B CHECKED: Allen Liu

DATE: MAR/21/2013 DRAWN: Y.Liu

PAGE: 5 OF 6 ERP: 1201005947





SPEC NO: DSAK5173 APPROVED: WYNEC REV NO: V.5B CHECKED: Allen Liu DATE: MAR/21/2013 DRAWN: Y.Liu PAGE: 6 OF 6 ERP: 1201005947